

- **Designed for WLAN IF Applications**
- **Low Insertion Loss**
- **5.0 x 5.0 x 1.7 mm Surface-Mount Case**
- **Differential or Single Ended Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)**

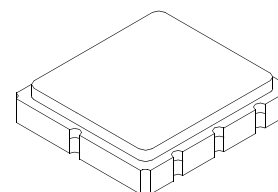


Absolute Maximum Ratings

| Rating | Value | Units |
|--|----------------|-------|
| Maximum Incident Power in Passband | +10 | dBm |
| Maximum DC Voltage Between any Two Terminals | 30 | VDC |
| Operable Temperature Range | -45 to +125 | °C |
| Specification Temperature Range | -10 to +85 | °C |
| Storage Temperature Range | -40 to +85 | °C |
| Suitable for lead-free soldering - Maximum Soldering Profile | 260°C for 30 s | |

SF1174B

**374.00 MHz
SAW Filter**



SM5050-8

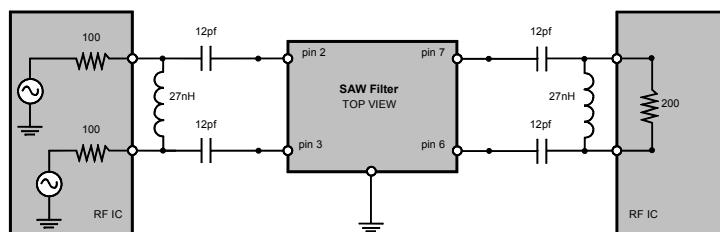
Electrical Characteristics

| Characteristic | Sym | Notes | Min | Typ | Max | Units |
|---|--------|---------|---------|-----|------|-------------------|
| Nominal Center Frequency | f_c | 1 | 374.000 | | | MHz |
| Passband Insertion Loss at f_c 3 dB Passband Amplitude Ripple over $f_c \pm 7.0$ MHz Group Delay Variation over $f_c \pm 7.0$ | IL | 1, 2 | | 8.7 | 10.0 | dB |
| | BW_3 | | 17 | 23 | | MHz |
| | | | | 0.8 | 1.0 | dB _{P-P} |
| | GDV | | | 61 | 100 | ns _{P-P} |
| Rejection $f_c - 100$ to $f_c - 33$ MHz $f_c - 33$ to $f_c - 22$ MHz $f_c - 22$ to $f_c - 16.5$ MHz $f_c + 16.5$ to $f_c + 22$ MHz $f_c + 22$ to $f_c + 43$ MHz $f_c + 43$ to $f_c + 100$ MHz | | 1, 2, 3 | 45 | 54 | | dB |
| | | | 40 | 53 | | |
| | | | 30 | 40 | | |
| | | | 30 | 44 | | |
| | | | 35 | 48 | | |
| | | | 40 | 49 | | |
| Operating Temperature Range | T_A | 1 | -10 | | +85 | °C |

| | |
|---|-------------------------------------|
| Differential Input / Output Impedance Match | External L-C |
| Case Style | SM5050-8 5 X 5 mm Nominal Footprint |
| Lid Symbolization (YY=year, WW=week, S=shift) | 447, <u>YYWWWS</u> |

Electrical Connections

| Connection | Terminals |
|-------------------|------------|
| Port 1 Hot | 2 |
| Port 1 Gnd Return | 3 |
| Port 2 Hot | 6 |
| Port 2 Gnd Return | 7 |
| Case Ground | All others |



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

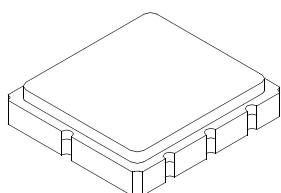
NOTES:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production"
5. and "ENG" or "E" indicates "engineering prototypes."
6. The design, manufacturing process, and specifications of this filter are subject to change.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

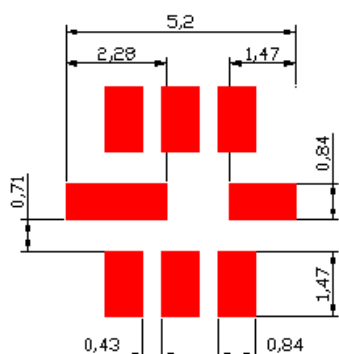
SM5050-8 Case

8-Terminal Ceramic Surface-Mount Case

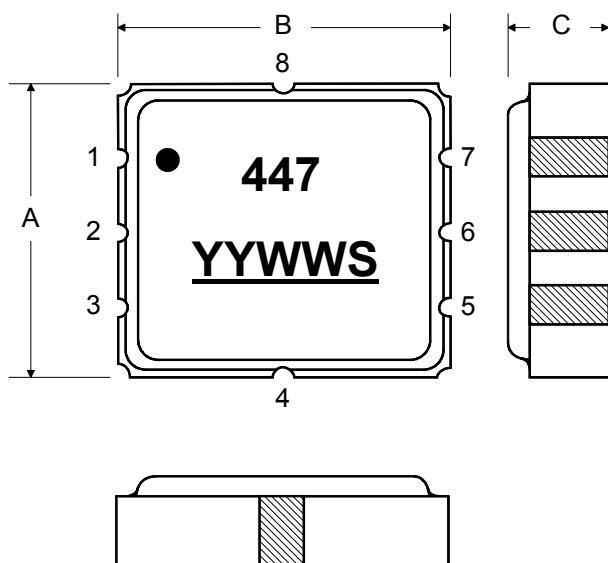
5.0 X 5.0 mm Nominal Footprint



PCB FOOTPRINT



TOP VIEW



Case Dimensions

| Dimension | mm | | | Inches | | |
|-----------|------|------|------|--------|--------|--------|
| | Min | Nom | Max | Min | Nom | Max |
| A | 4.8 | 5.0 | 5.2 | | 0.1968 | |
| B | 4.8 | 5.0 | 5.2 | | 0.1968 | |
| C | | | 1.7 | | | 0.0669 |
| D | | 2.08 | | | 0.0818 | |
| E | | 1.17 | | | 0.046 | |
| F | | 0.64 | | | 0.0252 | |
| G | 2.39 | 2.54 | 2.69 | | 0.100 | |

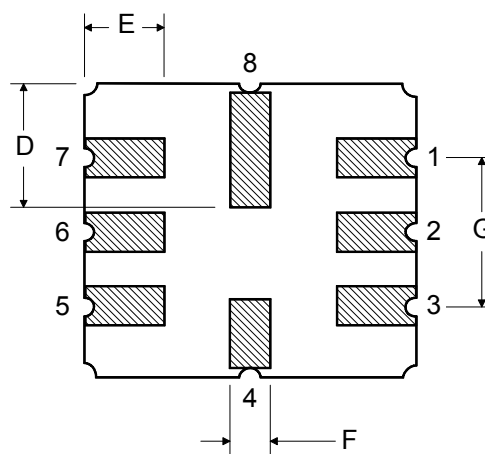
Electrical Connections

| Connection | | Terminals |
|------------------------|---------------------|------------------|
| Port 1 | Differential Input | 2,3 |
| Port 2 | Differential Output | 6,7 |
| | Ground | All others |
| Single Ended Operation | | Return is ground |
| Differential Operation | | Return is hot |
| Dot indicates Pin 1 | | |

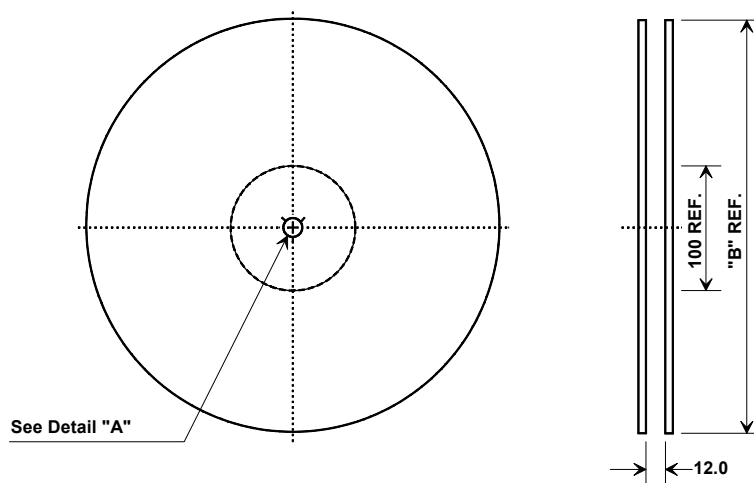
Materials

| | |
|------------------------|---|
| Solder Pad Termination | Au plating 30 - 60 μ nches (76.2-152 μ M) over 80-200 μ nches (203-508 μ M) Ni. |
| Lid | Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μ nches Thick |
| Body | Al ₂ O ₃ Ceramic |
| Pb Free | |

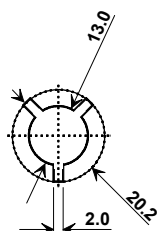
BOTTOM VIEW



Tape and Reel Specifications

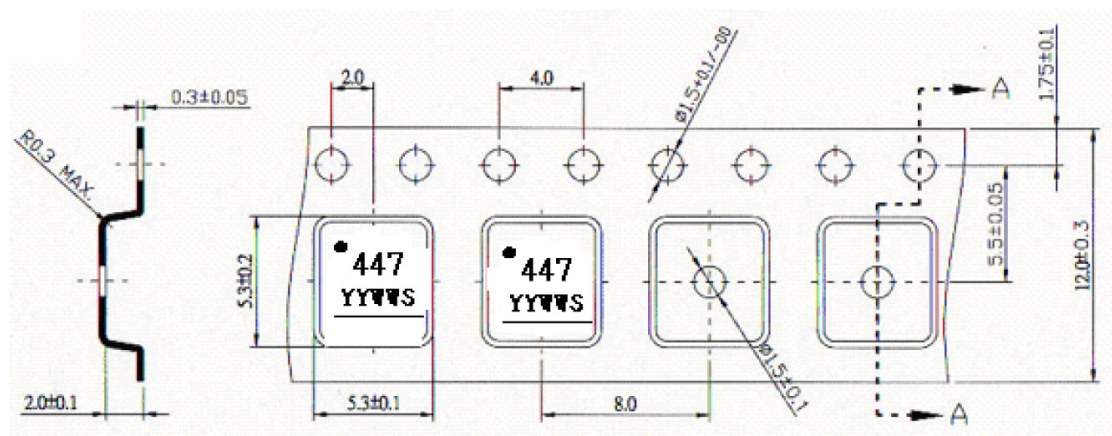


| “B” | | Quantity Per Reel |
|--------|-------------|-------------------|
| Inches | millimeters | |
| 7 | 178 | 500 |
| 13 | 330 | 2000 |



COMPONENT ORIENTATION and DIMENSIONS

| Carrier Tape Dimensions | |
|-------------------------|---------|
| Ao | 5.3 mm |
| Bo | 5.3 mm |
| Ko | 2.0 mm |
| Pitch | 8.0 mm |
| W | 12.0 mm |



USER DIRECTION OF FEED

